

FIG.1A

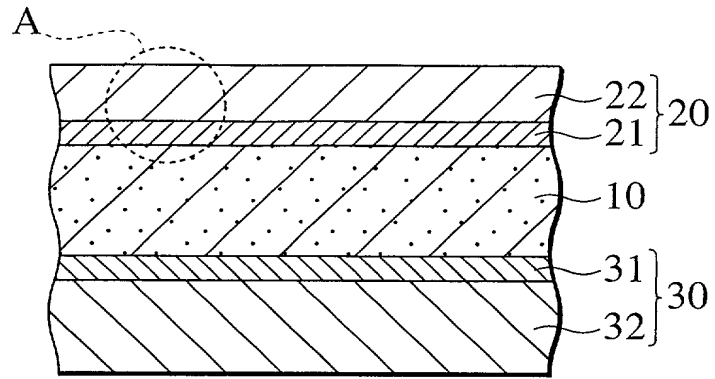


FIG.1B

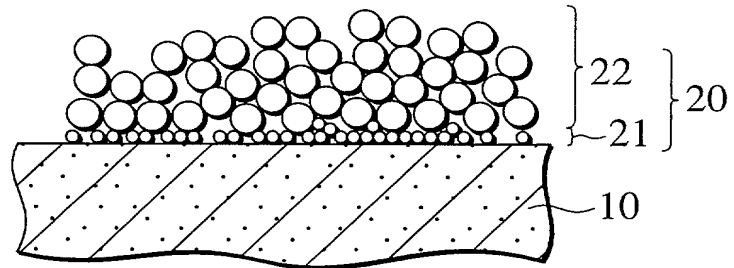


FIG.2

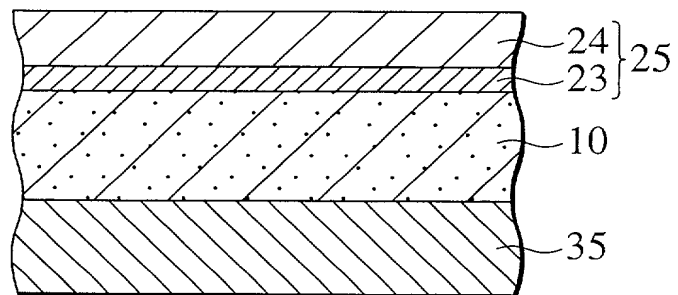


FIG.3A

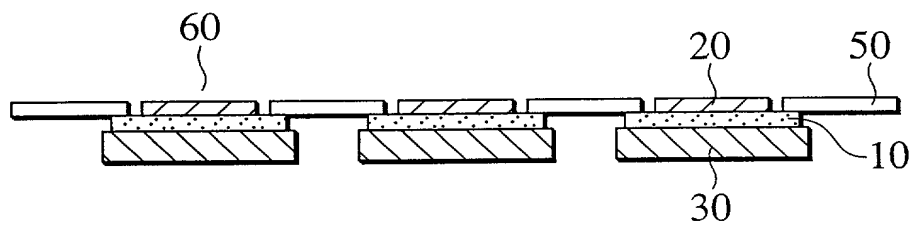


FIG.3B

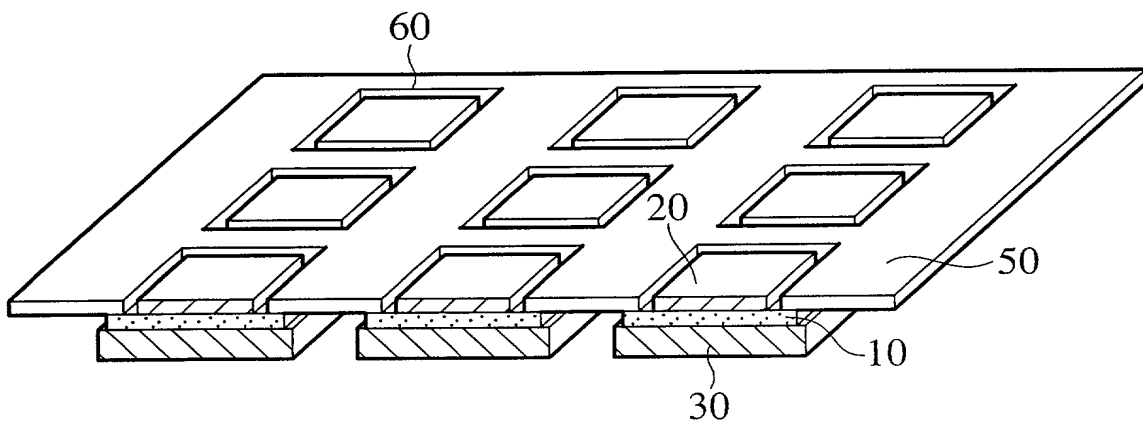


FIG.4A

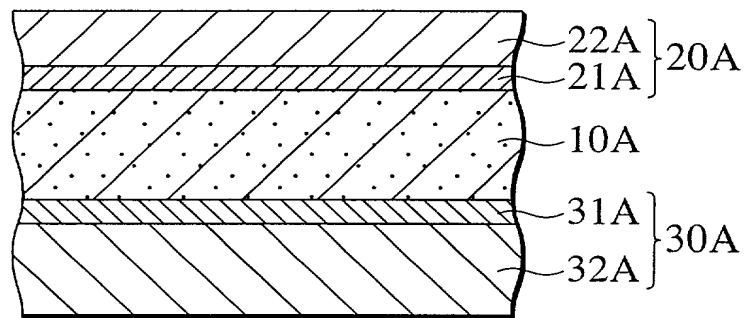


FIG.4B

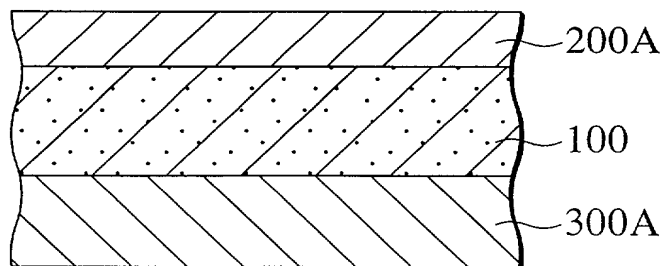


FIG.4C

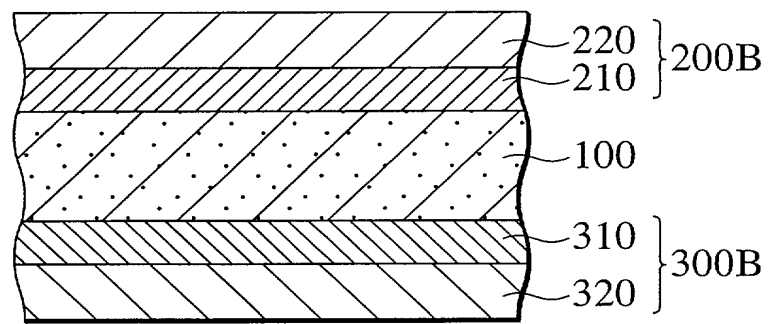


FIG.4D

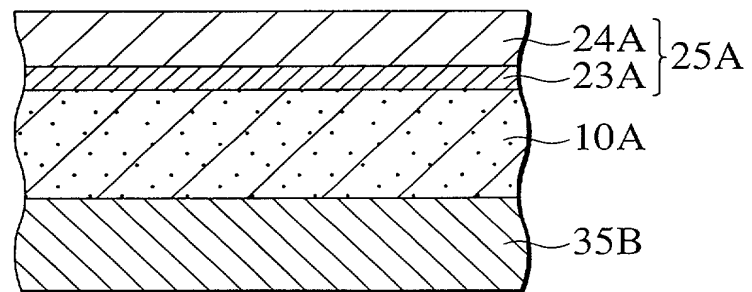


FIG.5

Table. 1

	Air electrode (Ag)		Fuel electrode (Ni)		Peeling property	Cell property (i=0.4A/cm ² hour)
	Lower layer	Upper layer	Lower layer	Upper layer		
Example 1	Sputtering film : 50 nm	Splayed film : 15 μ m	Sputtering film : 50 nm	Splayed film : 35 μ m	OK	0.130W/cm ²
Comparative example 1	—	Splayed film : 15 μ m	—	Splayed film : 35 μ m	OK	0.12W/cm ²
Example 2	Splayed film : 0.1 μ m	Splayed film : 15 μ m	Splayed film : 0.1 μ m	Splayed film : 35 μ m	OK	0.127W/cm ²
Comparative example 2	—	Splayed film : 15 μ m	—	Splayed film : 35 μ m	×	0.123W/cm ²
Comparative example 3	Sputtering film : 2 μ m	Splayed film : 15 μ m	Sputtering film : 2 μ m	Splayed film : 35 μ m	×	0.11W/cm ²

*) The lower layer and the upper layer in the air electrode are an adhering cathode layer and an electricity collecting cathode layer respectively.

*) The lower layer and the upper layer in the fuel electrode are an adhering anode layer and an electricity collecting anode layer respectively.

FIG.6

Tabl. 2

Example No	Electrical collecting cathode layer		Adhering cathode layer				Cell resistance (Ω)
	Material	Particle diameter	Material	Method	Baking temperature ($^{\circ}\text{C}$)	Adhesion strength	Resistance (Ω)
Example 3	LSC	5 μm	Ag	Sputtering	800	○	2.3
Example 4	LSC	5 μm	Bismuth oxide	EB deposition	800	○	2.5
Example 5	LSC	5 μm	Ag+LSC	Sputtering	850	○	2.3
Example 6	LSC	5 μm	Bismuth oxide+ glass frit	Screen printing	900	○	2.8
Comparative example 4	LSC	5 μm	Nothing	—	1100	○	350
Comparative example 5	LSC	5 μm	Nothing	—	800	×	12.5
Comparative example 6	LSC	5 μm	Ag	Sputtering	850	○	56.2
Comparative example 7	LSC	5 μm	Bismuth oxide+ glass frit	Screen printing	500	×	3.5